Build Up HDI (Standard)

HDI08_2+4b+2_1,00_35_engl

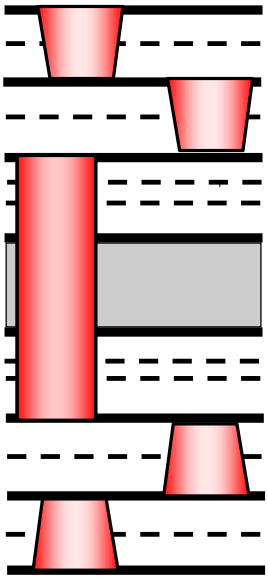
8 - Layers

Core: 0,25 mm Cu 35/35 µm

WE-Articel No.:

2 + 4B + 2

Customer:



layer description		configuration	Raw-Material	CU	PREPREG	Final Thickness	Customer requirements
Customer	WE					[µm]	[µm]
	TOP/VS		Foil	12 µm	1)	12	
					1 x 1080	60	
	2		Foil	12 µm		30	
					1 x 1080	58	
	3		Foil	12 µm		35	
					2 x 1080	133	
	4			35 µm		33	
			0,250 mm			250	
	5			35 µm		33	
					2 x 1080	133	
	6		Foil	12 µm		35	
					1 x 1080	58	
	7		Foil	12 µm		30	
					1 x 1080	60	
	BOT/RS		Foil	12 µm	1)	12	
					total material thickness:	972	

1) copper thickness outer layers: appr. 55 µm

Note: Lamination thickness for Prepregs depending on layout characteristics.

final lamination thickness:	**1,00**	+/-	0,08	mm			Date:	Engineer:
thickness with electro plated Cu:	1,09	+/-	0,11	mm				
total thickness with soldermask	1,15	+/-	0,13	mm				
customer requirement		+/-		mm	point:			

prepared: on	by	checked: on	by	approved: on	by	revision	page:
25.04.2006	**S. Keller**	04.05.2006	M.Kress	25.04.2006	R. Schönholz	00	18+